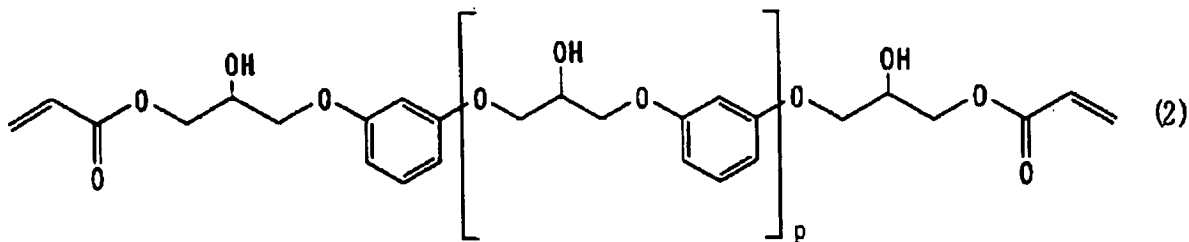
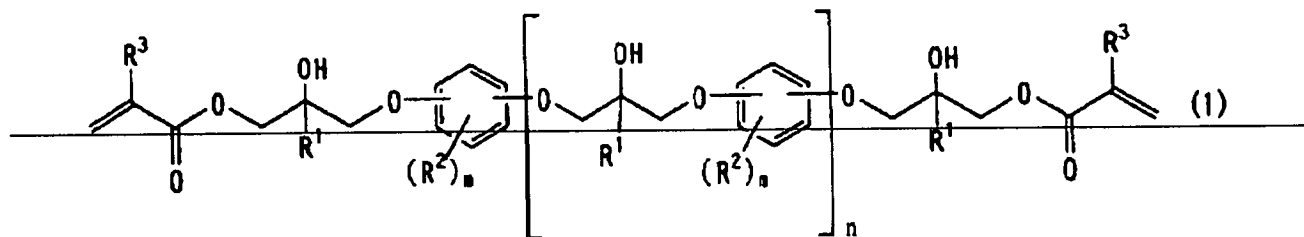


## Amendments to the Claims

This listing of claims replaces all prior versions, and listings, of claims in the application.

### Listing of claims:

1. (Currently amended) A sealant for liquid crystals comprising as essential ingredients (a) a radiation curable resin represented by the general formula ~~(1)~~ (2):



wherein  $R^1$  ~~represents a hydrogen atom or a methyl group,  $R^2$  represents a hydrogen atom, a halogen atom, a hydroxyl group, a linear, branch or cyclic monovalent alkyl group having 1 to 10 carbon atoms, or an alkoxy group having 1 to 10 carbon atoms,  $m$  represents an integer of 1 to 4, and may be the same or~~

~~different, R<sup>3</sup> represents a hydrogen atom or a methyl group, and the number n of the repeating units is a positive number in the range of 0 to 20;~~ the number p of the repeating units is a positive number in the range of 0 to 20, which is obtained by subjecting resorcin diglycidyl ether to acrylic acid in an amount equivalent to the number of epoxy groups in the molecule;

(b) a radical photopolymerization initiator; and (c) an inorganic filler having an average particle diameter of 3  $\mu\text{m}$  or less.

2. (Canceled)

3. (Currently amended) The sealant for liquid crystals according to claim 1 ~~or~~ 2, wherein the radiation curable resin (a) has a content of 30% by weight to 80% by weight based on the total amount of the sealant for liquid crystals.

4. (Currently amended) The sealant for liquid crystals according to claim 1 ~~or~~ 2, wherein the radiation curable resin (a) has a viscosity of 30 to 500 Pa.s.

5. (Canceled)

6. (Currently amended) The sealant for liquid crystals according to claim 1 ~~or~~ 2 wherein the radical type photopolymerization initiator (b) is a carbazole initiator.

7. (Currently amended) The sealant for liquid crystals according to claim 1-~~or~~2, further comprising (d) an epoxy resin and (e) a heat-curing agent.

8. (Original) The sealant for liquid crystals according to claim 7, wherein the epoxy resin (d) is an epoxy resin which does not elute into the liquid crystals in an amount of 0.5% by weight or more based on the liquid crystals when the epoxy resin is brought directly into contact with the liquid crystals whose amount is 10 times of the epoxy resin and is allowed to stand at 120°C for 1 hour.

9. (Previously presented) The sealant for liquid crystals according to claim 7, wherein the heat-curing agent (e) is a dihydrazide.

10. (Original) The sealant for liquid crystals according to claim 9, wherein the dihydrazide is a dihydrazide having a skeleton of isophthalic dihydrazide and/or valine hydantoin.

11. (Previously presented) The sealant for liquid crystals according to claim 7, wherein the heat-curing agent (e) is a polyhydric phenol.

12. (Currently amended) The sealant for liquid crystals

according to claim 1-~~or~~-2, further comprising (f) a silane coupling agent.

13. (Original) The sealant for liquid crystals according to claim 12, wherein the silane coupling agent is a silane coupling agent having an amino group.

14. (Currently amended) A liquid crystal display cell which is sealed with a cured product of a sealant for liquid crystals according to claim 1-~~or~~-2.

15. (Currently amended) A process for producing a liquid crystal display cell comprising dropping liquid crystals inside a sealant for liquid crystals according to claim 1-~~or~~-2 formed on a substrate and attaching another substrate thereto.